

Anand Meled

List of Publications by Year in descending order

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2682572
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all docs

4
docs citations

4
times ranked

22
citing authors

#	ARTICLE	IF	CITATIONS
1	Tribological, Thermal, and Kinetic Characterization of 300-mm Copper Chemical Mechanical Planarization Process. Japanese Journal of Applied Physics, 2011, 50, 05EC02.	1.5	15
2	Analyses of Diamond Disk Substrate Wear and Diamond Microwear in Copper Chemical Mechanical Planarization Process. Journal of the Electrochemical Society, 2010, 157, H250.	2.9	11
3	Pad Wear Analysis during Interlayer Dielectric Chemical Mechanical Planarization. ECS Journal of Solid State Science and Technology, 2012, 1, N103-N105.	1.8	2
4	Slurry-Induced Pad Wear Rate in Chemical Mechanical Planarization. Electrochemical and Solid-State Letters, 2010, 13, H52.	2.2	1